

IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies. Related Materials and Processes

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Schedule of Scope to Certificate of Approval Independent Testing Laboratory

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1. Environmental and Reliability Testing of Electronic Components, Assemblies, and Related Materials

Description test	Standard	Remarks
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA includes FIB (Focused Ion Beam), SEM (Scanning electron microscope)	MIL-STD-883 Method 2018.4 JESD22A121 JESD201	Or customer specified test
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA, includes Electrical Analysis and Physical Analysis with Sample Preparation (Decap, X-section, etc)	MIL-STD-883 Method 2009.9 IPC-A-610; IPC-A-600 MIL-STD-883 Method 2008.4 JESD22A121; JESD201 IPC-TM-650 2.1.1; IPC-6012	Or customer specified test
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA, includes NDE (Non-destructive Testing)	MIL-STD-883 Method 2012.7 J-STD-035; J-STD-020	Or customer specified test
2nd level integration platform service. (Includes Pre-SMT/SMT / Temperature Cycling test /Thermal Shock test/ Drop test/ Shock test / Vibration test/ Bending test / gross leak test /dye &pry test /solderability test /Wire Bond Shear&Wire Bond Pull test / Physical Dimensions measurement /Solder Ball Shear test /Die Shear test)	Industrial (JESD 47) ,JESD-22-A104/IPC-9701/MIL-STD-883 /JESD22-A106/JESD22-B104/JESD22-B110/JESD22-B103/JEITA ED-4702/IPC-JEDEC-9702/IEC 60068-2-21-2006/SEMI G86-0303/AEC-Q200-003/005/IPC-610F/IPC-7525/JEDEC JESD22-B102/JEDEC JESD22-B100	Or customer specified test
Accelerated environment reliability stress tests (Includes Pre-condition / MSL / Accelerated Temperature-Humidity test / Temperature-Humidity with bias test / Temperature Cycling test / Power and temperature cycling test / Low Temperature storage test / Highly Accelerated Stress Test/Autoclave Test//Thermal Shock Test)	JESD 47,J-STD-020, JESD22-series;IEC-60068-series, MIL-STD-202/750/810/883,JESDJP001; EIA-364-32C, EIAJED-4701, AEC-Q100;AEC-Q101, AEC-Q200,	Or customer specified test
Accelerated lifetime simulation tests. (Includes Operating Life test / Early life failure rate test/ Endurance and Data retention test / Electro-Migration /Miscellaneous test)	JESD 47,JESD22-A108/A117, JESD61, MIL-STD-202/750/810/883, AEC- Q100;AEC-Q101, AEC-Q200,	Or customer specified test
Electrostatic discharge test. (Including : HBM / MM / CDM / Latch Up / ESD Gun)	JESD 47 ,JEDEC22-A114/A115/C101, EIA/JESD78, ANSI JEDEC ESDA JS001/JS002; AEC-Q100-002/003/004/011, AEC-Q101-001/002/005, AEC-Q200- 002,JEITA ED4701; IEC61000-4-2, MIL- STD-883	Or customer specified test

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